

In the Claims:

Please rewrite Claims 11, 12, and 14-19 as follows.

Please cancel Claim 13 without prejudice.

11. (CURRENTLY AMENDED) A molded package with a disposable mold runner gate, comprising:

a substrate having a first surface and a second surface, wherein said first surface has a gating area;

conductive traces formed on said first surface of said substrate wherein some of said conductive traces are formed in said gating area of said first surface of said substrate;

a first number of electronic devices attached to said first surface of said substrate;

electrical connections between said electronic devices and said conductive traces;

input/output connections formed on said substrate;

electrical connections between said conductive traces and said input/output connections;

barrier material attached to said gating area of said substrate;

encapsulation material formed over a part of said barrier material attached to said gating area of said substrate, thereby forming a mold runner, wherein said barrier material and said encapsulation material are chosen so that the adhesion of said barrier material to said substrate is less than the adhesion of said barrier material to said encapsulation material; and

a cover of said encapsulation material formed over part of said substrate covering said first number of electronic devices.

12. (CURRENTLY AMENDED) The molded package with a disposable mold runner gate of claim 11 wherein said input/output connections comprise a ball grid array formed on said second surface of said substrate.

13. (CANCELLED) The disposable mold runner gate of claim 11 wherein some of said conductive traces are formed in said gating area of said first surface of said substrate.

14. (CURRENTLY AMENDED) The molded package with a disposable mold runner gate of claim 11 wherein said electrical connections between said electronic devices and said conductive traces comprise wire bonds.

15. (CURRENTLY AMENDED) The molded package with a disposable mold runner gate of claim 11 wherein said first number of electronic devices is one electronic device.

16. (CURRENTLY AMENDED) The molded package with a disposable mold runner gate of claim 11 wherein said electronic devices are integrated circuit elements.

17. (CURRENTLY AMENDED) The molded package with a disposable mold runner gate of claim 11 wherein said barrier material is polyimide tape.

18. (CURRENTLY AMENDED) The molded package with a disposable mold runner gate of claim 11 wherein said barrier material is high temperature plastic.

19. (CURRENTLY AMENDED) The molded package with a disposable mold runner gate of claim 11 wherein said encapsulation material is an encapsulating mold compound.